NEC
ELECTRON DEVICE

N-CHANNEL MOS FIELD EFFECT POWER TRANSISTOR

2SK875

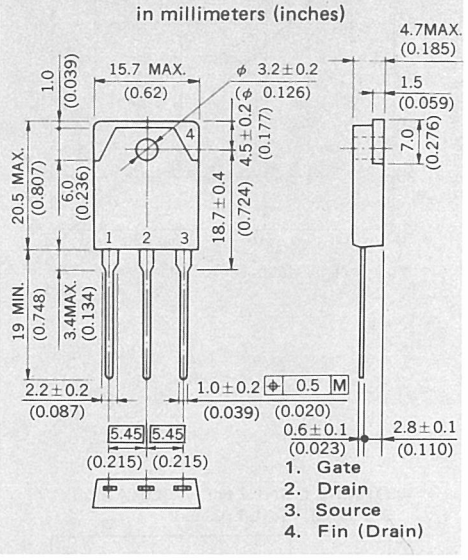
DESCRIPTION

The 2SK875 is N-channel MOS Field Effect Power Transistor designed for switching power supplies DC-DC converters.

FEATURES

- Suitable for switching power supplied, actuater controls, and pulse circuits.
- Low $R_{DS(on)}$
- No second breakdown

PACKAGE DIMENSIONS
in millimeters (inches)



ABSOLUTE MAXIMUM RATINGS

Maximum Temperatures

- Storage Temperature . . . . . −55 to +150 °C
- Channel Temperature . . . . . 150 °C Maximum

Maximum Power Dissipation (T_C = 25 °C)

- Total Power Dissipation . . . . . 120 W

Maximum Voltages and Currents (T_a = 25 °C)

- V_{DSS} Drain to Source Voltage . . . . . 450 V
- V_{GSS} Gate to Source Voltage . . . . . ±20 V
- $I_{D(DC)}$ Drain Current (DC) . . . . . ±12 A
- $I_{D(pulse)}$ Drain Current (pulse)* . . . . . ±48 A

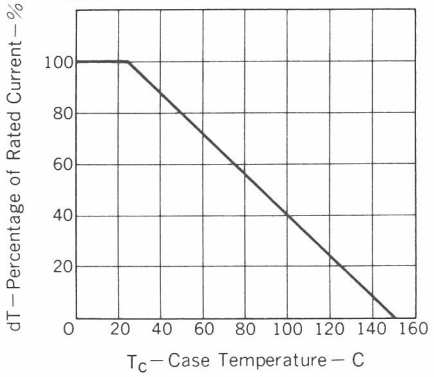
* PW ≦ 100 μs, Duty Cycle ≦ 2 %

ELECTRICAL CHARACTERISTICS (T_a = 25 °C)

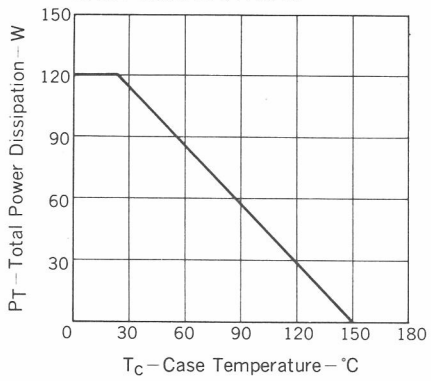
SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
I_{DSS}	Drain Leakage Current			100	μA	V_{DS} = 450 V, V_{GS} = 0
I_{GSS}	Gate to Source Leakage Current			±100	nA	V_{GS} = ±20 V, V_{DS} = 0
$V_{GS(off)}$	Gate to Source Cutoff Voltage	1.5		3.5	V	V_{DS} = 10 V, I_D = 1 mA
$\|y_{fs}\|$	Forward Transfer Admittance	5.0			S	V_{DS} = 10 V, I_D = 6 A
$R_{DS(on)}$	Drain to Source On-State Resistance		0.5	0.60	Ω	V_{GS} = 10 V, I_D = 6 A
C_{iss}	Input Capacitance		2000		pF	V_{DS} = 10 V, V_{GS} = 0, f = 1 MHz
C_{oss}	Output Capacitance		450		pF	
C_{rss}	Reverse Transfer Capacitance		120		pF	
$t_{d(on)}$	Turn-On Delay Time		30		ns	I_D = 6 A, V_{DD} ≒ 150 V, $V_{GS(on)}$ = 10 V, R_L = 25 Ω, R_{in} = 10 Ω
t_r	Rise Time		50		ns	
$t_{d(off)}$	Turn-Off Delay Time		100		ns	
t_f	Fall Time		50		ns	

TYPICAL CHARACTERISTICS (T_a = 25 °C)

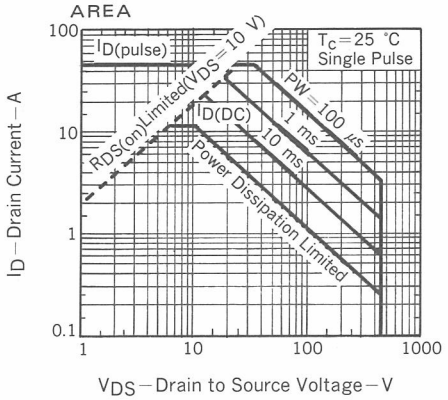
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



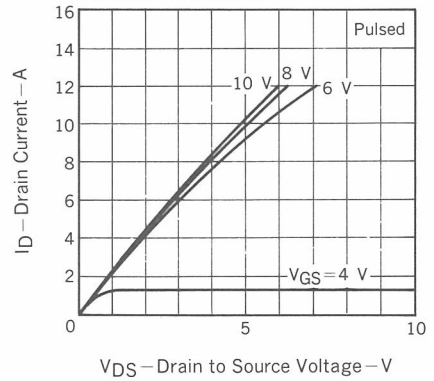
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



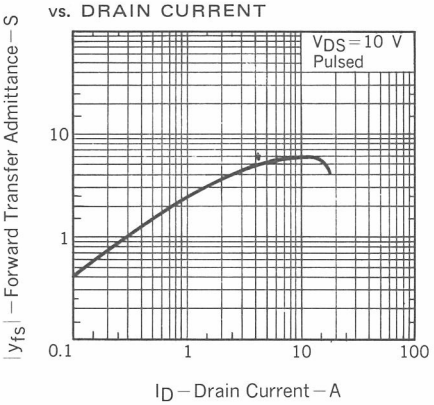
FORWARD BIAS SAFE OPERATING AREA



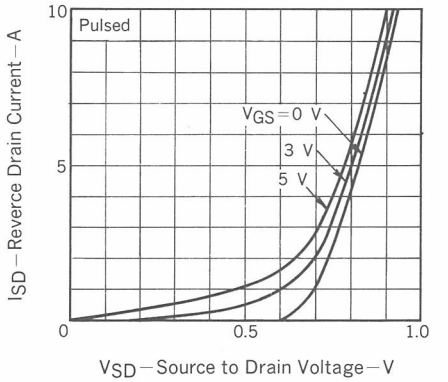
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



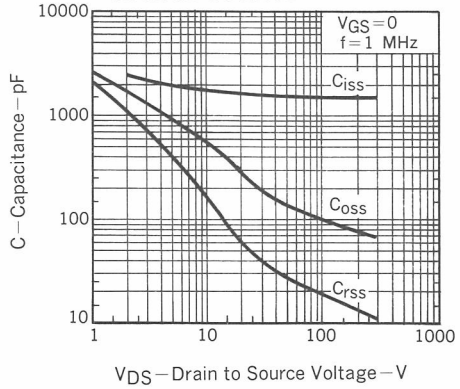
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



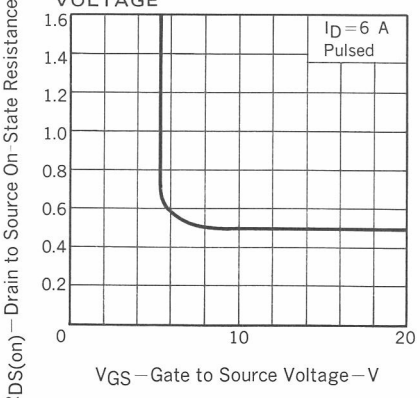
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



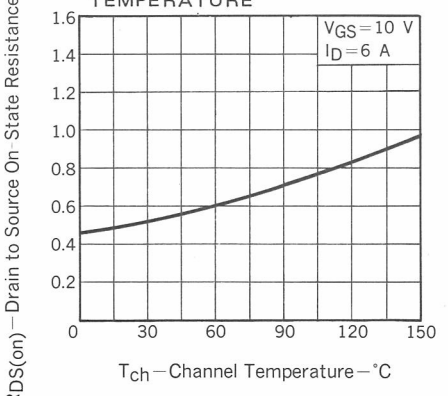
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



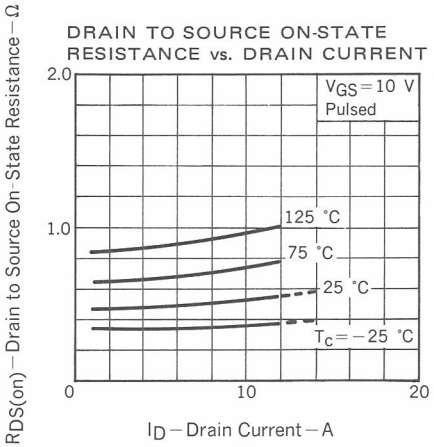
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



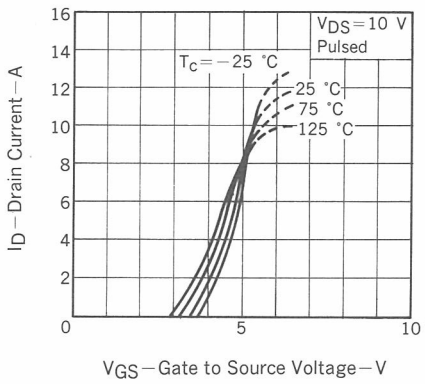
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



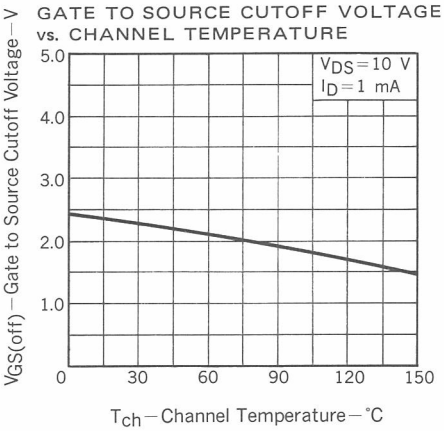
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



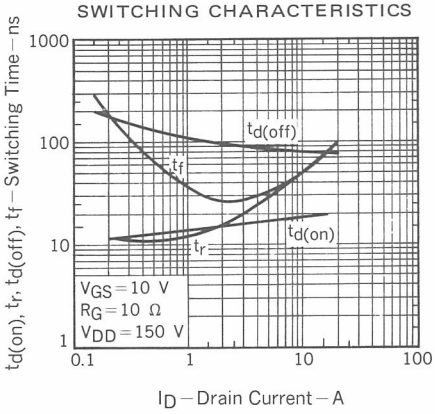
TYPICAL TRANSFER CHARACTERISTICS



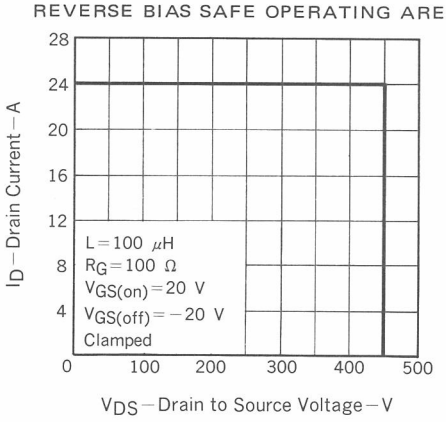
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



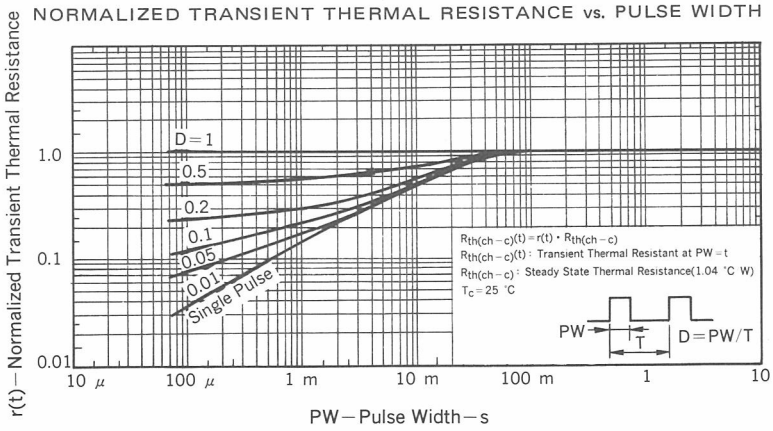
SWITCHING CHARACTERISTICS



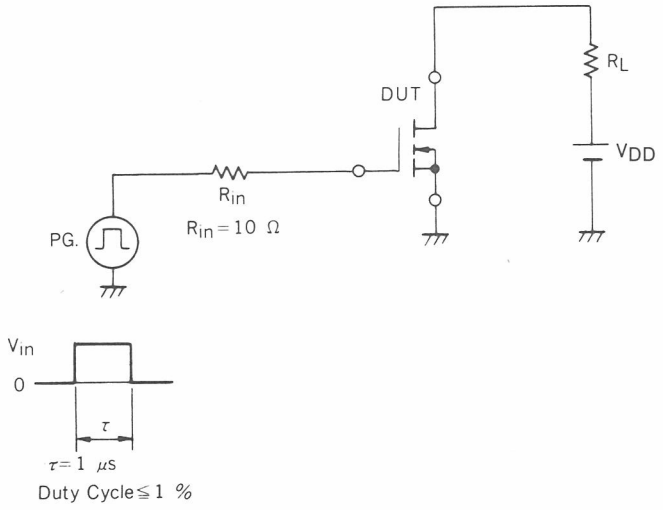
REVERSE BIAS SAFE OPERATING AREA

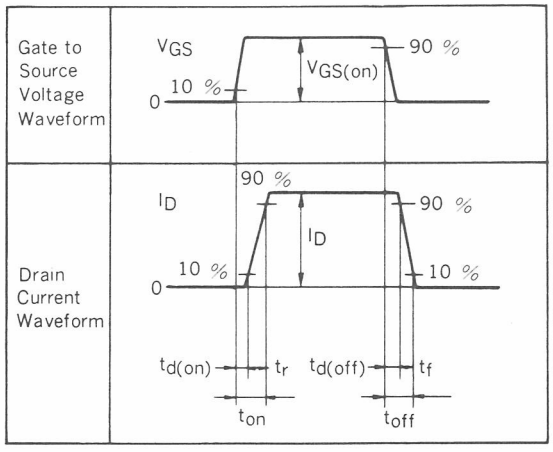


NORMALIZED TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

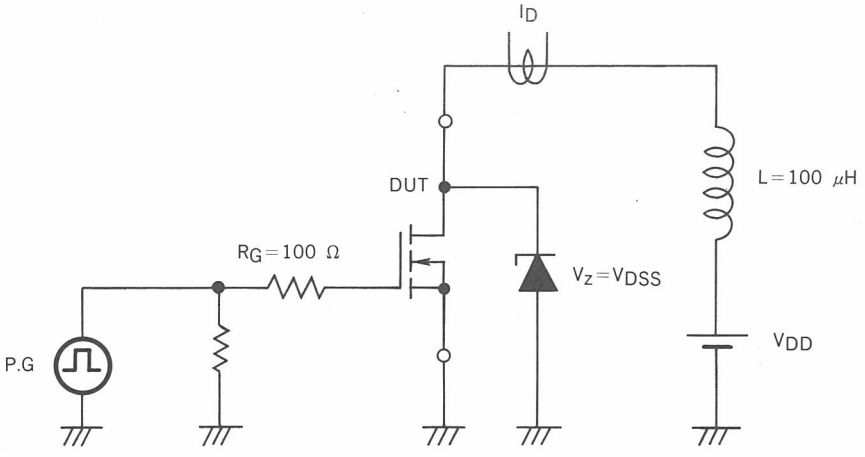


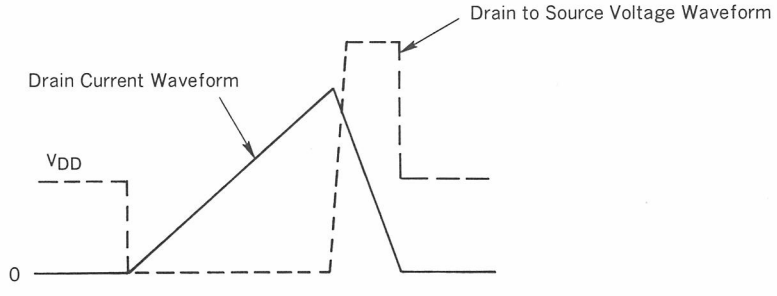
SWITCHING TIME TEST CIRCUIT





CLAMPED INDUCTIVE TEST CIRCUIT





Clamped Inductive Waveforms